

ABSTRACT OF DISCLOSURE

An inspecting apparatus for a semiconductor device having a match plate; a contact module combined with the match plate, including a radiation unit contacting a semiconductor device, and a test unit pressing leads of the semiconductor device; and a thermally conductive pad installed on a contacting face of the radiation unit of the contact module, to transfer heat from the semiconductor device to the radiation unit of the contact module. The present invention provides an inspecting apparatus for semiconductor devices that improves reliability of testing for durability of semiconductor devices against heat, and minimizes damage to the semiconductor devices during testing.